INTEGRATED CIRCUITS

Product specification Supersedes data of 2000 May 08 2003 Feb 04

Up-level Car radio Analog Signal Processor (CASP) Processor (CASP)

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18 PURCHASE OF PHILIPS I²C COMPONENTS

Up-level Car radio Analog Signal Processor (CASP) and TEA6880H

1 FEATURES

1.1 General

- I²C-bus compatible
- Digital alignment/adjustment via I2C-bus:
	- FM noise blanker sensitivity
	- FM stereo noise canceller
	- FM High Cut Control (HCC)
	- FM stereo separation.
- FM audio processing hold for RDS updating; holds the detectors for the FM weak signal processing in their present state
- FM bandwidth limiting; limits the bandwidth of the FM audio signal with external capacitors
- AM stereo input; AM stereo audio can be fed in at the pins for the de-emphasis capacitors; this will provide 8 dB of gain to the AM audio.

1.2 Stereo decoder and noise blanking

- FM stereo decoder
- Accepts FM multiplex signal and AM audio at input
- Pilot detector and pilot canceller
- De-emphasis selectable between 75 and 50 µs
- AM noise blanker: impulse noise detector and an audio hold.

1.3 Weak signal processing

• FM weak signal processing: six signal condition detectors, soft mute, stereo noise canceller (blend) and high cut control (roll-off).

1.4 Audio pre-amplifier

• Source selector for 6 sources: 2 stereo inputs external (A and B), 1 symmetrical stereo input (C), 1 symmetrical mono input (D), 1 internal stereo input (AM or FM) and 1 chime/diagnostic mono input

- Volume 1 control from +20 to −56 dB in 1 dB steps; programmable 20 dB loudness control included
- Volume 2 control from 0 to −56 dB in 1 dB steps, −56, −58.5, −62, −68 dB and mute
- Programmable loudness control with bass boost as well as bass and treble boost
- Treble control from −14 to +14 dB in 2 dB steps
- Bass control from −18 to +18 dB in 2 dB steps with selectable characteristic
- Analog Step Interpolation (ASI) minimizes pops by smoothing out the transitions in the audio signal when a switch is made
- Audio Blend Control (ABC) minimizes pops by automatically incrementing the volume and loudness controls through each step between their present settings and the new settings
- Rear Seat Audio (RSA) can select different sources for the front and rear speakers
- Chime input: can be sent to any audio output, at any volume level
- Chime adder circuit: chime input can also be summed with left front and/or right front audio, or be turned off

2 GENERAL DESCRIPTION

The TEA6880H is a monolithic bipolar integrated circuit providing the stereo decoder function and ignition noise blanking facility combined with source selector and tone/volume control for AM/FM car radio applications. The device operates with a power supply voltage range from 7.8 to 9.2 V and a typical current consumption of 40 mA.

3 ORDERING INFORMATION

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4 QUICK REFERENCE DATA

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5 BLOCK DIAGRAM

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6 PINNING

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7 FUNCTIONAL DESCRIPTION

7.1 Stereo decoder

The MPX input is the null-node of an operational amplifier with internal feedback resistor. Adapting the stereo decoder input to the level of the MPX signal, coming from the FM demodulator output, is realized by the value of the input series resistor R_{IN} . To this input a second source (AM detector output) can be fed by current addition.

The input amplifier is followed by an integrated 4th order Bessel low-pass filter with a cut-off frequency of 80 kHz. It provides necessary signal delay for FM noise blanking and damping of high frequency interferences coming to the stereo decoder input.

Output of this filter is fed to the soft mute control circuitry, the output is voltage to current converted and then fed to phase detector, pilot detector and pilot canceller circuits, contained in the stereo decoder PLL block. For regeneration of the 38 kHz subcarrier, a PLL is used. The fully integrated oscillator is adjusted by means of a digital auxiliary PLL into the capture range of the main PLL. The auxiliary PLL needs an external reference frequency (75.4 kHz) which is provided by the TEA6840H. The required 19 and 38 kHz signals are generated by division of the oscillator output signal in a logical circuitry. The 19 kHz quadrature phase signal is fed to the 19 kHz phase detector, where it is compared with the incoming pilot tone. The DC output signal of the phase detector controls the oscillator (PLL).

The pilot presence detector is driven by an internally generated in-phase 19 kHz signal. Its pilot dependent DC output voltage is fed to a threshold switch, which activates the pilot indicator bit and turns the stereo decoder to stereo operation. The same DC voltage is used to control the amplitude of an anti-phase internally generated 19 kHz signal. In the pilot canceller, the pilot tone is compensated by this anti-phase 19 kHz signal.

The pilot cancelled signal is fed to the matrix. There, the side signal is demodulated and combined with the main signal to left and right audio channel. Compensation for roll-off in the incoming MPX signal caused by IF filters and FM demodulator is typically realized by an external compensation network at pin MPXIN, individual alignment is achieved by I²C-bus controlled amplification of the side signal (DAA). A smooth mono to stereo takeover is achieved by controlling the efficiency of the matrix with help of the SNC peak detector.

The matrix is followed by the FM noise suppression gates, which are combined with FM single poles and High Cut Control (HCC).

The single pole is defined by internal resistors and external capacitors. From the gate circuits audio is fed to the switchable de-emphasis, where the demodulated AM stereo signal can be fed in. After de-emphasis the signal passes to the output buffers and is fed to the radio input of the source selector. For HCC, the time constant of the single pole contained in the output buffer can be changed to higher values. This function is controlled by an average detector contained in the multipath and fading detector.

7.2 FM noise blanker

The input of the ignition noise blanker is coupled to the MPXRDS input signal and to the LEVEL input. Both signals are fed via separate 120 kHz filters and rectifiers to an adder circuit. The output signal of the adder circuit is fed in parallel to the noise detector and the interference detector. The noise detector is a negative peak detector. Its output controls the trigger sensitivity (prevention to false triggering at noisy input signals) and the gain of the MPX high-pass filter. The output of the interference detector, when receiving a steep pulse, fires a monoflop, contained in the pulse former circuitry. The time constant of the monoflop is defined by an internal capacitor and its output activates the blanking gates in the audio.

7.3 AM noise blanker

The AM noise blanking pulse is derived from the AM audio signal which is fed into pin AMNBIN with the help of a peak-to-average comparator. The blanking time is set by a pulse former with external capacitor. The blanking pulse is fed to the gate in the AM audio path and out to pin AMHOLD to operate the gate built into the external AM stereo processor.

7.4 Multipath/fading detection and weak signal control

For FM signal quality dependent controls there is built-in a combination of six detectors driven by the level information direct, by the AC components on the level via a 20 kHz band-pass filter (AM wideband) or the high notes present at the FM demodulator output via a 60 kHz high-pass filter (ultrasonic noise). The relation between DC level and the AC components is programmable by the I^2C -bus (2 bits each). Output of level buffer, AM wideband detector and ultrasonic noise detector are analog-to-digital converted and readable by the I2C-bus.

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For the time of fast RDS updating soft mute, SNC and HCC can be put on hold and the AM wideband peak detector and the ultrasonic noise peak detector are put on reset by a switch signal delivered from the TEA6840H via pin FMHOLD.

The six separate detecting circuits are:

- 1. The AM wideband noise peak detector is driven from a 20 kHz band-pass filter connected to the level buffer output. The time constant is defined by an external capacitor at pin TWBAM2. The output voltage of the detector is analog-to-digital converted by 3-bit.
- 2. The AM wideband noise average detector is driven from a 20 kHz band-pass filter connected to the level buffer output. The time constant is defined by an external capacitor at pin TWBAM1. The output of the detector is connected to the Stereo Noise Control (SNC) circuit.
- 3. The ultrasonic noise peak detector is driven from a 60 kHz high-pass filter connected to the MPX signal from pin MPXRDS. The time constant is defined by an external capacitor at pin TUSN2. The output voltage of the detector is analog-to-digital converted by 3-bit.
- 4. The ultrasonic noise average detector is driven from a 60 kHz high-pass filter connected to the MPX signal from pin MPXRDS. The time constant is defined by an external capacitor at pin TUSN1. The output of the detector is connected to soft mute control and stereo noise control circuits.
- 5. For soft mute and high cut control purposes an average detector with externally defined time constant (TMUTE) is provided. The detector is driven by level output only. Soft mute as well as high cut control can be switched off by the I²C-bus.
- 6. The stereo noise control peak detector with externally defined time constant (TSNC) is driven by DC level output, AM wideband and ultrasonic noise outputs. It provides the stereo blend facility (SNC). Starting point and slope of stereo blend can be chosen by the I²C-bus controlled reference voltage.

7.5 Tone/volume control

The tone/volume control part consists of the following functions:

- Source selector
- Loudness
- Volume 1
- Treble
- Bass
- Volume 2
- Rear Seat Audio (RSA) selector
- Chime adder
- Analog step interpolation
- Audio blend control.

The stages loudness, volume 1, bass and volume 2 include the Analog Step Interpolation (ASI) function. This minimizes pops by smoothing out the transitions in the audio signal during switching. The transition time is I ²C-bus programmable in a range of 1 : 24 in four steps.

The stages loudness, volume 1 and volume 2 also have the Audio Blend Control (ABC) function. This minimizes pops by automatically incrementing the volume and loudness controls through each step between their present settings and the new settings. The speed of the ABC function is correlated with the transition time of the ASI function.

All stages are controlled via the 1^2C -bus.

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7.5.1 SOURCE SELECTOR

The source selector allows the selection between 6 sources:

- 2 external stereo inputs (ALI, ARI, BLI and BRI)
- 1 external symmetrical stereo input (CLIP, CRIP and CCOM)
- 1 external symmetrical mono input (MONOP and MONON)
- 1 internal stereo input (AM/FM)
- 1 chime/diagnostic mono input (CHIME).

Via the chime/diagnostic mono input a chime input signal can be sent to any audio output, at any volume level.

7.5.2 LOUDNESS

The output of the source selector is fed into the loudness circuit via the external capacitors C_{KVL} (pins LOPO and LOPI) and C_{KVR} (pins ROPO and ROPI). Depending on the external circuits for the left and the right channel only a bass boost or bass and treble boost is available. With the external circuits shown in Figs 13 and 15 the curves from Figs 14 and 16 will be obtained (without influence of C_{KVI} respectively C_{KVR}).

7.5.3 VOLUME 1

The volume 1 control follows behind the loudness circuit. The control range of volume 1 is between +20 and −36 dB in steps of 1 dB.

7.5.4 TREBLE

The output signal of the volume 1 control is fed into the treble control stage. The control range is between +14 and −14 dB in steps of 2 dB. Fig.20 shows the control characteristic with external capacitors of 10 nF.

7.5.5 BASS

The bass control is the next stage. The characteristic of the bass curves depends upon the external circuits connected to pins LBO and LBI (left channel) and pins RBO and RBI (right channel) and also upon the setting of bit BSYM (MSB of the bass control byte). When $BSYM = 1$, an equalizer characteristic is obtained and when $BSYM = 0$, a shelving characteristic is obtained.

Figures 17 and 18 show the bass curves with an external circuit of 2 \times 220 nF capacitors and a resistor of 3.3 kΩ for each channel with different values for BSYM. Figure 19 shows the bass curves with an external capacitor of 47 nF for each channel and BSYM = 0, for boost and cut.

7.5.6 VOLUME 2

The four volume 2 blocks are located at the end of the tone/volume control. In addition to volume control (same settings as volume 2) also the balance and fader functions are performed by individual attenuation offsets for the four attenuators. The control range of these attenuators is 56 dB in steps of 1 dB and additional the steps −58.5 dB, −62 dB, −68 dB and a mute step.

7.5.7 RSA SELECTOR

The RSA selector provides the possibility to select an alternative source for the rear channels. In this event rear channels are only controlled by volume 2 function.

7.5.8 CHIME ADDER

With the chime adder circuit the chime input signal can be summed with the left front and/or right front audio, or be turned off.

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8 LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

Notes

- 1. Machine model (R = 0Ω , C = 200 pF).
- 2. Human body model ($R = 1.5$ k Ω , $C = 100$ pF).

9 THERMAL CHARACTERISTICS

10 CHARACTERISTICS

FM part: input signal V_{i(MPX)(p-p)} = 1.89 V; m = 100% ($\Delta f = \pm 75$ kHz, f_{mod} = 400 Hz); de-emphasis of 75 µs and series resistor at input R_{IN} = 182 k Ω ; FM audio measurements are taken at pins LOPO and ROPO.

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Tone part: $R_S = 600 \Omega$; $R_L = 10 k\Omega$, AC-coupled; $C_L = 2.5$ nF; CLK = square-wave (5 to 0 V) at 100 kHz; stereo source = A channel input; volume 1 attenuator = 0 dB; loudness = 0 dB, off; volume 2 attenuators = 0 dB; bass linear; treble linear; input voltage = 1 V, f = 1 kHz. Tone part audio measurements are taken at pins RF and LF. $V_{CC} = 8.3$ to 8.7 V; $V_{SS} = 0$ V; $T_{amb} = 25$ °C; unless otherwise specified.

This IC shall not radiate noise in the audio system such that it disturbs any other circuit. This IC shall also not be susceptible to the radiation of any other circuit.

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Notes to the characteristics

1. Intermodulation suppression; Beat Frequency Components (BFC):

$$
IM2 = \frac{V_{o(signal)}(at 1 kHz)}{V_{o(spurious)}(at 1 kHz)}; f_s = (2 \times 10 kHz) - 19 kHz
$$

$$
IM3 = \frac{V_{o(signal)}(at 1 kHz)}{V_{o(spurious)}(at 1 kHz)}; f_s = (3 \times 13 kHz) - 38 kHz
$$

measured with 91% mono signal; f_{mod} = 10 kHz or 13 kHz; 9% pilot signal.

2. RDS suppression:

 $\alpha_{57(RDS)} = \frac{V_{o(signal)}(at 1 kHz)}{(at 1 kHz + 25 s)}$ $=\frac{O(\text{signal})}{V_{\text{o(spurious)}}(\text{at 1 kHz ±23 Hz})}$

measured with 91% stereo signal; f_{mod} = 1 kHz; 9% pilot signal; 5% RDS subcarrier $(f_s = 57$ kHz; $f_{mod} = 23$ Hz; AM m = 0.6).

3. Subsidiary Communication Authorization (SCA):

$$
\alpha_{67} = \frac{V_{o(signal)}(at 1 kHz)}{V_{o(spurious)}(at 9 kHz)} \ ; \ f_s = (2 \times 38 kHz) - 67 kHz
$$

measured with 81% mono signal; f_{mod} = 1 kHz; 9% pilot signal; 10% SCA subcarrier $(f_s = 67$ kHz, unmodulated).

4. Adjacent Channel Interference (ACI):

$$
\alpha_{114} = \frac{V_{o(signal)}(at 1 kHz)}{V_{o(spurious)}(at 4 kHz)}; f_s = 110 kHz - (3 \times 38 kHz)
$$

$$
\alpha_{190} = \frac{V_{o(signal)}(at 1 kHz)}{V_{o(spurious)}(at 4 kHz)}; f_s = 186 kHz - (5 \times 38 kHz)
$$

measured with 90% mono signal; $f_{mod} = 1$ kHz; 9% pilot signal; 1% spurious signal $(f_s = 110$ kHz or 186 kHz, unmodulated).

5. AM stereo audio buffer gain:

$$
G = 20 \log \frac{V_{\text{LOPO}}}{V_{\text{DEEML}}}; G = 20 \log \frac{V_{\text{ROPO}}}{V_{\text{DEEMR}}}
$$

6. Input resistance for AM stereo left and right:

$$
R_{i(DEEML)} = \frac{\Delta V_{DEEML}}{\Delta I_{i(DEEML)}}; R_{i(DEEMR)} = \frac{\Delta V_{DEEMR}}{\Delta I_{i(DEEMR)}}
$$

7. Attenuation of blanking gate:

$$
\alpha_{\text{AMGATE}} = 20 \log \frac{V_{\text{AMPCAP}}}{V_{\text{AMPCAP}}} \text{ at gate close}
$$

8. TWBAM1 DC voltage coefficient:

$$
VC_{TWBAM1} = \frac{V_{TWBAM1} \text{ with AC voltage at LEVEL}}{V_{TWBAM1} \text{ without AC voltage}}
$$

9. TUSN1 DC voltage coefficient:

$$
VC_{TUSN1} = \frac{V_{TUSN1} \text{ with AC voltage at MPXRDS}}{V_{TUSN1} \text{ without AC voltage}}
$$

10. TSNC DC voltage coefficient:

$$
VC_{TSNC} = \frac{V_{TSNC} \text{ with AC voltage at MPXRDS}}{V_{TSNC} \text{ without AC voltage}}
$$

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11. TSNC DC voltage coefficient:

$$
VC_{TSNC} = \frac{V_{TSNC} \text{ with AC voltage at LEVEL}}{V_{TSNC} \text{ without AC voltage}}
$$

12. TUSN2 DC voltage coefficient:

$$
VC_{TUSN2} = \frac{V_{TUSN2} \text{ with AC voltage at MPXRDS}}{V_{TUSN2} \text{ without AC voltage}}
$$

13. TWBAM2 DC voltage coefficient:

$$
VC_{TWBAM2} = \frac{V_{TWBAM2} \text{ with AC voltage at LEVEL}}{V_{TWBAM2} \text{ without AC voltage}}
$$

14. Start of channel separation:

$$
\alpha_{cs(stat)} = \left| 20 log \frac{V_{LOPO(AC)}}{V_{ROPO(AC)}} \right|
$$

15. Slope of channel separation:

$$
\alpha_{\text{cs(slope)}} = \left| 20 \log \frac{V_{\text{LOPO(AC)}}}{V_{\text{ROPO(AC)}}} \right|
$$

16. AC attenuation for start and slope of HCC:

$$
\alpha_{\text{HCC}(10 \text{ kHz})} = 20 \log \frac{V_{\text{LOPO}, \text{ROPO}}}{V_{\text{LOPO}, \text{ROPO}} \text{ without High Cut active}}
$$

17. Crosstalk between bus inputs and signal outputs:

$$
\alpha_{ct} = 20 \log \frac{V_{bus(p-p)}}{V_{o(rms)}}
$$

18. The characteristics are in accordance with the I²C-bus specification, with the exception that the data hold time $t_{HD:DAT}$ must be at least 1 μ s. This specification, *"The l²C-bus and how to use it"*, can be ordered using the code 9398 393 40011.

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11 I2C-BUS PROTOCOL

Table 1 Write mode

Table 3 Chip address byte

Notes

- 1. Defined by address pin ADR.
- 2. 0: receiver and 1: transmitter.

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11.1 Read mode: 1st data byte

Table 4 Format of 1st data byte

Table 5 Description of 1st data byte bits

Table 6 Level setting ADC

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11.2 Read mode: 2nd data byte

Table 7 Format of 2nd data byte

Table 8 Description of 2nd data byte

Table 9 Ultrasonic noise ADC

Table 10 AM wideband noise ADC

11.3 Subaddress byte for write

Table 11 Format for subaddress byte

Table 12 Description of subaddress byte

Table 13 Selection of data byte

Note

11.4 Write mode: subaddress 0H

Table 14 Format of data byte Alignment 0 (ALGN0)

Table 15 Description of ALGN0 bits

Table 16 Setting of AM/FM mode

Note

1. MPX input (MPXIN) and AM input (AMHIN) muted, stereo decoder in mono mode and de-emphasis terminals (DEEML and DEEMR) are audio signal inputs.

Table 17 Setting of start of muting $(\alpha_{\text{MULTE}} = 6 \text{ dB})$

Data byte ALGN2: MSL0 = 1, MSL1 = 1

Data byte ALGN0

Fig.4 Soft mute attenuation versus V_{TMUTE} and V_{TUSN1} input voltage (fixed slope).

11.5 Write mode: subaddress 1H

Table 18 Format of data byte Alignment 1 (ALGN1)

Table 19 Description of ALGN1 bits

Table 20 Setting of ultrasonic noise sensitivity ($V_{MPXRDS(AC)} = 350$ mV)

Data byte ALGN1

Fig.5 Ultrasonic noise peak and average detector output voltage versus MPX signal input and stereo noise control peak detector output voltage versus MPX signal input.

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Table 21 Setting of AM wideband sensitivity ($V_{LEVEL(AC)} = 400$ mV)

0 200

−2.2 1 1 1 −3.3 1 0 −4.9 0 1 −6.5 0 0 V_{TWBAM2} 6 (1) (2) (3) VTWBAM1 V TSNC 5 (V) 1 2 3 4 MHB410 (4)

400 600

SLOPE (V/V) $\qquad \qquad$ AWS1 $\qquad \qquad$ AWS0

VLEVELAC(24kHz)p-p (mV)

800

1000

Data byte ALGN1

 $0\frac{L}{0}$

Fig.6 AM wideband peak and average detector output voltage versus level AC signal input and stereo noise control peak detector output voltage versus level AC signal input.

Table 22 Setting of channel separation alignment

Note

1. Not tested; function not guaranteed.

11.6 Write mode: subaddress 2H

Table 23 Format of data byte Alignment 2 (ALGN2)

Table 24 Description of ALGN2 bits

Table 25 Setting of soft mute slope alignment

Data byte ALGN0: MST0 = 0, MST1 = 0

Data byte ALGN2

Fig.7 Soft mute attenuation versus input voltages V_{TUSN1} and V_{TMUTE} (fixed start).

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Table 26 Setting of stereo noise control slope alignment ($V_{TSNC} = 0.72V_{TUSN1}$ without AC)

Data byte ALGN2: SST = 1000

Data byte ALGN2

Fig.8 Channel separation versus voltage at pins TSNC, TWBAM1 and TUSN1 (fixed start).

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Table 27 Setting of stereo noise control start alignment ($\alpha_{cs} = 6$ dB)

Data byte ALGN2: SSL1 = 0, SSL0 = 1

Data byte ALGN2

Fig.9 Channel separation versus voltage at pins TSNC, TWBAM1 and TUSN1 (fixed slope).

11.7 Write mode: subaddress 3H

Table 28 Format of data byte Alignment 3 (ALGN3)

Table 29 Description of ALGN3 bits

Table 30 Setting of noise blanker sensitivity

Table 31 Setting of alignment for start of high cut control ($\alpha_{10kHz} = 3$ dB)

Fig.10 High cut control versus V_{TMUTE} (fixed slope).

Data byte ALGN3: HST1 = 1, HST0 = 1

Data byte ALGN3

Fig.11 High cut control versus V_{TMUTE} (fixed start).

11.8 Write mode: subaddress 4H

Table 33 Format of data byte Source Selector (SSEL)

Table 34 Description of SSEL bits

Table 35 ASI/ABC speed selection $(C_{ASICAP} = 15 \text{ nF})$

Table 36 Selected source for rear outputs

Note

Table 37 Selected source for main control part

Note

1. Not tested; function not guaranteed.

11.9 Write mode: subaddress 5H

Table 38 Format of data byte Bass control (BASS)

Table 39 Description of BASS bits

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Note

11.10 Write mode: subaddress 6H

Table 41 Format of data byte Treble control (TRBL)

Table 42 Description of TRBL bits

Table 43 Setting of treble control level

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11.11 Write mode: subaddress 7H

Table 44 Format of data byte Loudness control (LOUD)

Table 45 Description of LOUD bits

Table 46 Attenuation of loudness block

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Note

11.12 Write mode: subaddress 8H

Table 47 Format of data byte Volume 1 control (VOLU1)

Table 48 Description of VOLU1 bits

Table 49 Attenuation of volume 1 block

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Note

11.13 Write mode: subaddress 9H

Table 50 Format of data byte Volume 2, left front (VOL2_LF)

Table 51 Description of VOL2_LF bits

Table 52 Attenuation of volume 2 left front

Up-level Car radio Analog Signal Op-level Call Taulu Arialog Signal
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Note

11.14 Write mode: subaddress AH

Table 53 Format of data byte Volume 2, right front (VOL2_RF)

Table 54 Description of VOL2_RF bits

Table 55 Attenuation of volume 2 right front

Note

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11.15 Write mode: subaddress BH

Table 56 Format of data byte Volume 2, left rear (VOL2_LR)

Table 57 Description of VOL2_LR bits

Table 58 Attenuation of volume 2 left rear

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Note

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11.16 Write mode: subaddress CH

Table 59 Format of data byte Volume 2, right rear (VOL2_RR)

Table 60 Description of VOL2_RR bits

Table 61 Attenuation of volume 2 right rear

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Note

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12 INTERNAL CIRCUITRY

Table 62 Equivalent pin circuits

54 TMUTE 55 MPXRDS 56 TSNC 57 MPXIN 58 FMNCAP PIN SYMBOL **COULD AS A SYMBOL** 54 MHB385 55 MHB407 56 MHB386 57 MHB372 58 MHB387

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99-12-27

13 PACKAGE OUTLINE

SOT319-2 MO-112 MO-112 MO-112 SOT319-2

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14 SOLDERING

14.1 Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "Data Handbook IC26; Integrated Circuit Packages" (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

14.2 Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferable be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

14.3 Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
	- larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
	- smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

• For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C. A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

14.4 Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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14.5 Suitability of surface mount IC packages for wave and reflow soldering methods

Notes

- 1. For more detailed information on the BGA packages refer to the "(LF)BGA Application Note" (AN01026); order a copy from your Philips Semiconductors sales office.
- 2. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the "Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods".
- 3. These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
- 4. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- 5. Wave soldering is suitable for LQFP, TQFP and QFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- 6. Wave soldering is suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

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15 DATA SHEET STATUS

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

16 DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition - Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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18 PURCHASE OF PHILIPS I2C COMPONENTS

Purchase of Philips I²C components conveys a license under the Philips' I²C patent to use the components in the I2C system provided the system conforms to the I2C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

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Contact information

For additional information please visit **http://www.semiconductors.philips.com**. Fax: **+31 40 27 24825** For sales offices addresses send e-mail to: **sales.addresses@www.semiconductors.philips.com**.

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